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Replacement Sheet (Abstract)

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ABSTRACT

1 This invention provides an electronic component mounting method capable of
2 effectively utilizing a self-alignment effect even if a mounting interval of electronic
3 components is small. This method includes the steps of detecting a printing position of
4 a solder paste on the circuit board and mounting an electronic component. When a solder
5 paste on a circuit board having a land formed thereon is printed and an electronic
6 component is mounted, the printing position of the solder paste of the circuit board is
7 detected by a printing position detecting device included in an inspecting apparatus.
8 Then, the electronic component is mounted by using the detected printing position of the
9 solder paste as a reference by an electronic component mounting apparatus.